

DF-APPLICATIONS - KEEP SOLDERING SIMPLE

WWW.DF-APPLICATIONS.COM

- Bench top vapour phase reflow system
- Max product format 460 x 205mm
- Plug&play-operation



JS460

| °c† | Schritt 1 | Schritt 2 • EnergyCut : 0 |
|-----|-----------|------------------------------|
| | | EnergyCut : 1 |
| | | EnergyCut : 2 |
| | / | |
| | / | |
| | | |



| Vapour Phase Refl | ow Ofen |
|---------------------|---|
| | Step: 0001 Time: 0001 s Target: 0150 °C Cyde: 000077 Time: 0001 s |
| | |
| Program: 1 START | STOP |

- Æffective heat transfer by condensation
- ✓ Uniform soldering temperature
- ✓ PCB-temperature controlled profiling
- ✓ Gradient regulation with EnergyCut
- ✓ Data-storage via USB

4" Touchpanel

- Automatic process incl. physically limited soldering temperature
- ☆ Soldering temperature 160-240°C



- Stainless steel soldering chamber
- Window for optical solder observation
- Single phase power supply, 208-240VAC
- Low power consumption, max 1 kW/h
- System dimensions:
- 590 x 540 x 350mm (I x w x h), Weight: 25kg